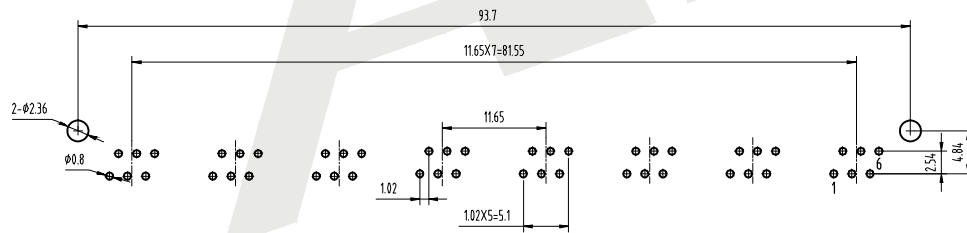
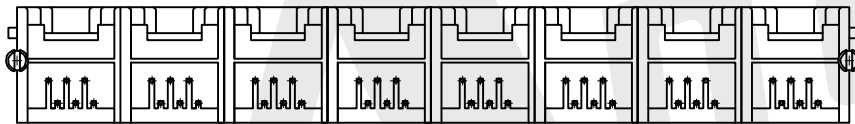
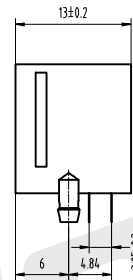
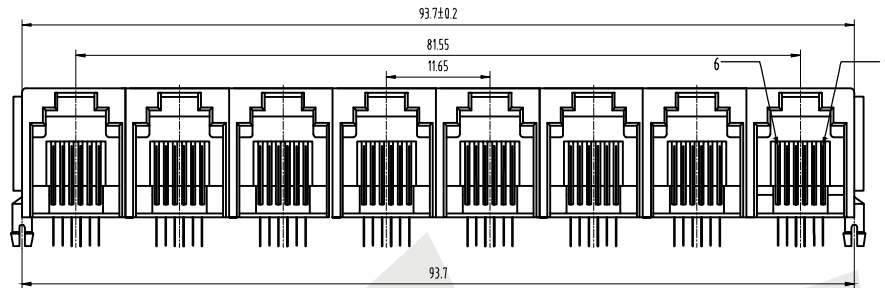


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL:GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL:PHOSPHOR BRONZE t=0.3mm
3. PLATING:SELECTING GOLD PLATING $1\mu \sim 50\mu$ "OVER NICKEL IN CONTACT AREA. 150μ " TIN PLATIN.OVER NICKEL IN SOLDER AREA
4. SHIELD:0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

1. VOLTAGE RATING:125VAC RMS
2. CURRENT RATING:1.5AMP
3. CONTACT RESISTANCE:30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILIT:750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER:1 LB MIN

REVRONMENTAL

1. STORAGE:-40° C TO 85° C
2. OPERATION:0° C TO 70° C

Order code:

ATRJ5522 - 6P - 6C - X - A - F - A

① ② ③ ④ ⑤ ⑥ ⑦

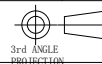
- ① SERIES NO:
- ② NUMBER OF POSITIONS(8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact PIating
- G0:Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3:10U" Gold
- G4:15U" Gold
- G5:30U" Gold
- SN:Tin
- ⑤ Shield
- A:W/O Shield
- B:Half Shield
- C:Shield W/Eml
- D:Shield W/O Eml
- ⑥ Ports
- A:1X1P
- B:1X2P
- C:1X4P
- D:1X5P
- E:1X6P
- F:1X8P
- ⑦ With Panel or not
- A:With panel
- B:Without panel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm

DRAW Wu Feng Rong DATE 11/09/2019

CHECK BobYang DATE 11/09/2019



ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: RJ11 Jack Side entry,
Full Plastic, 1X8P with panel

DRAWING NO: ATRJ5522-6P6C-X-A-F-A

PRODUCT NO: ATRJ5522-6P6C-X-A-F-A

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		